# INTEL 45NM CORE 2 MICROARCHITECTURE

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#### Microarchitecture Overview

- # Efficiency Enhancements
- \* Enhanced Dynamic Acceleration Technology
- Results

#### MICROARCHITECTURE OVERVIEW

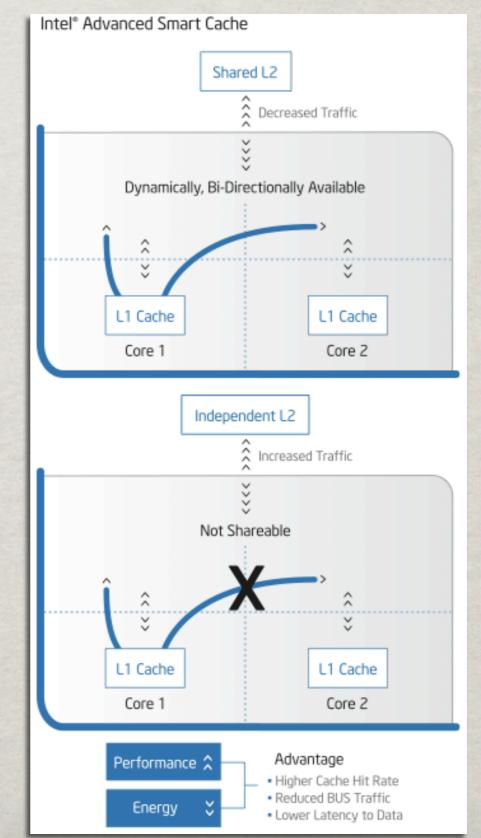
- Microarchitecture Overview
  - Transistor Innovations
  - % Cache
  - Wide Dynamic Execution
  - Macrofusion
  - Speeds
- # Efficiency Enhancements
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#### **TRANSISTOR INNOVATION**

- # High-k Metal Gate silicon technology
  - # Hafnium-based high-k gate dielectrics
    - significant reduction in electrical leakage
  - Approximately twice the transistor density
  - Approximately 30 percent reduction in transistor switching power
  - More than 20 percent faster transistor switching speed or more than 5 times reduction in source-drain leakage power
  - Greater than 10 times reduction in transistor gate oxide leakage
  - Considered to be the "biggest change in transistor technology since the introduction of polysilicon gate MOS transistors in the late 1960s"

#### **CACHE INNOVATIONS**

- Uses 24-way set associative "smart" cache
- Between 6 and 12 MB shared L2 cache
  - 50% more than previous family
- Advanced Smart Cache
  - # multi-core optimized cache
  - \* each core can utilize up to 100 percent of available L2 cache
  - \* when a core requires minimal cache requirements, a more active core can take over an inactive core's share



## WIDE DYNAMIC EXECUTION

- # 14 stage pipeline
- Wider execution core
  - \* each core can process up to four instructions simultaneously (up from three)
- Improved brach predictor algorithm
- Advanced Dynamic Execution engine
- Deeper instruction buffers
  - \* provides greater execution flexibility



#### MACROFUSION

- common instruction pairs combined into a single internal instruction (microop)
  - \* example: compare followed by a conditional jump
  - # takes place during the decoding stage
- # further facilitated by an enhanced ALU
  - single cycle execution of combined instruction pairs
- \*\* extended to micro-op fusion
  - macro-ops broken down into smaller micro-ops
  - micro-ops fused and executed together
  - reduces the number of micro-ops handled by out-of-order logic by more than 10 percent



- # greater than 3 GHz frequency in some versions
- # front-side bus up to 1.6 GHz
  - # greatly improved over previously available 1.066 and 1.333 GHz

## **EFFICIENCY ENHANCEMENTS**

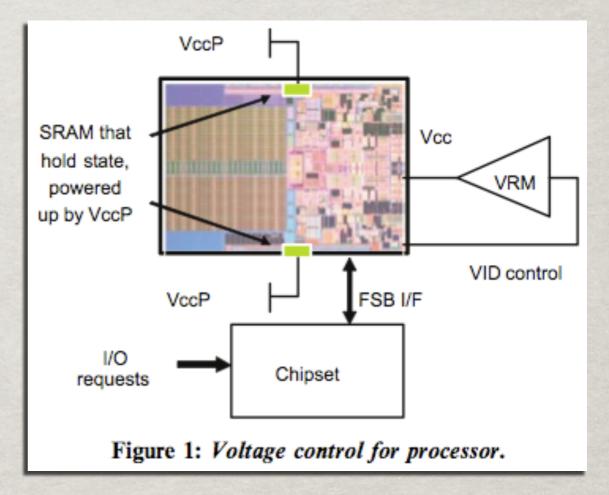
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- # Efficiency Enhancements
  - Deep Power Down
  - Server Idle Power Improvements
  - Desktop Idle Power Improvements
- Enhanced Dynamic Acceleration Technology
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## DEEP POWER DOWN (DPD)

- # Idle Power State
- In mobile platforms, consuming several watts of power while idle degrades battery life significantly
- Processor Running States
  - C0 running state; the only state in which the processor is executing instructions
  - C1-2 higher numbered states consume less power with higher exit latency
  - C3 processor Phased Locked Loop (PLL) is shut down; turns off all clocks in the chip
  - \* C4 voltage applied to the processor in C3 lowered to reduce leakage
  - Intermediate states (e.g. C1E) achieve lower leakage with Vcc reduction yet maintain cache coherent state with low exit latency

- In 65nm Core family, C5 state was implemented Enhanced Deeper Sleep state
  - \* Vcc reduced further, below cache retention voltage
  - \* only enough voltage to retain core state
  - leakage per transistor is low, but still accumulates to significant levels due to number of transistors

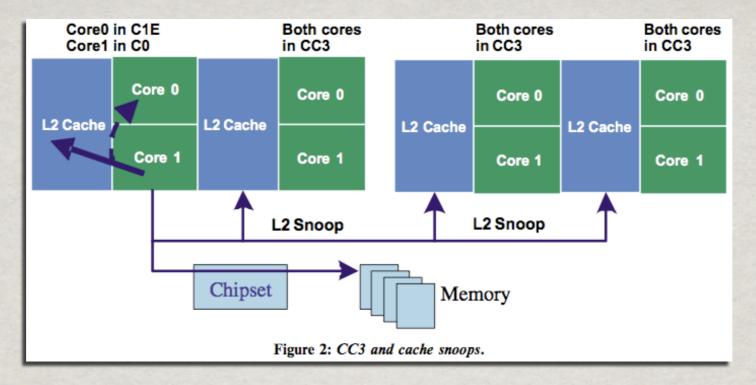
- In DPD (45nm Core 2 family), critical processor state is saved in dedicated SRAM on-chip
- \* powered by I/O power supply for the chip (VccP)
- \* core voltage reduced to very low level via Voltage Regulator Module(VRM)
- # equivalent to the Vcc core being powered off; does not consume power



- # upon a break event:
  - \* processor signals the VRM to ramp the Vcc back up
  - # re-locks PLLs
  - # turns clocks back on
  - internal reset to clear states
  - # restores core state from SRAM
  - \* opens up L2 cache
- # all steps completed in 150-200µs in processor hardware
  - # transparent to operating system and power-management software

## SERVER IDLE POWER IMPROVEMENTS (CC3)

- \* Targeted at single-socket and multi-socket workstations and servers
- Memory access from a core in a multi-socket environment generates snoops to all other cores and sockets
  - Snoop activity accounts for 30 percent of active core power
  - Idle state cores had to be woken up to respond to the snoop
  - Goal is to avoid snoops into idle cores
- Prior to the 45nm Core 2 family, idle cores were put into a snoop-able state -Core C1



- Idle cores now can be put into a non-snoop-able state Core C3
  - # first-level caches are flushed to L2 cache
  - prevents cross-core snoops
- Additional latency to enter CC3 is insignificant (less than 1µs)
  - CC3 can replace CC1 with no effect on software and operating systems
  - In cases where additional latency can't be tolerated, CC3 state can be exposed by the ACPI interface as C2
    - Operating system power management can choose CC1 or CC3
- Expected power consumption saving of about 10 percent

### DESKTOP IDLE POWER IMPROVEMENTS

- Focused on reducing the overall energy usage
- Deeper Sleep state
  - prior to the Penryn family, processors relied on autohalt and Stop Grant states
  - Penryn family processors use Deeper Sleep state to lower idle power consumption
  - The processor communicates to the platform through the:
    - Graphics Memory Controller Hub (GMCH)
    - # I/O Controller Hub (ICH)
    - The GMCH and the ICH can then power off portions of themselves required to service processor requests when the processor tells them it is in the Deeper Sleep state

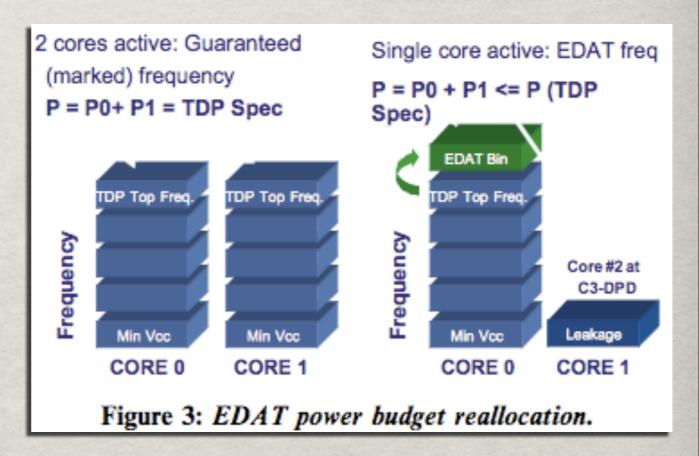
- Deeper Sleep state reduces voltage to the processor
  - processor cannot execute instructions
  - state is still retained
- Power consumption about 50 percent lower than Autohalt and Stop Grant states
- Communicates Deeper Sleep state to VRM
  - WRM can then shut down all but one phase
  - Active phase is boosted in addition to power saved
- Exposed in ACPI tables as C3 state
- Longer latency to memory traffic and interrupt response
  - # dude to having to ramp up voltage before responding to memory snoops and interrupts
  - BIOS configured exit latency tuned down to minimum level to compensate
  - no noticeable adverse impact

## ENHANCED DYNAMIC ACCELERATION TECHNOLOGY

- Microarchitecture Overview
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- \* Enhanced Dynamic Acceleration Technology
  - DAT Overview
  - \* Enhancements
  - EDAT Principles
- Results

## **DAT OVERVIEW**

- Power-management feature first introduced in 65nm Core 2 mobile processors
- Increases single threaded performance by using power headroom unused by idle cores
  - \* total power consumption remains within the specified TDP
- 10 percent frequency boost to single-threaded applications on mobile platforms



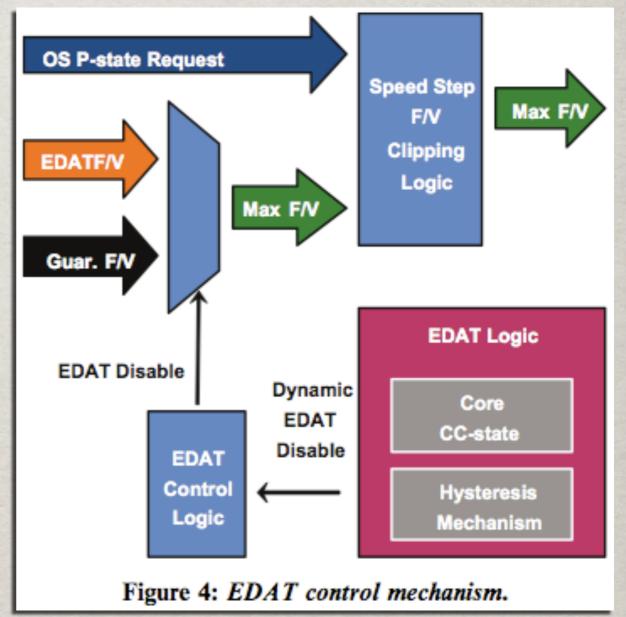
### ENHANCEMENTS

- # Hysteresis mechanism allows tolerance of short wake-up intervals of the idle core
  - # EDAT frequency retained
  - Reduced the number of transitions in and out of EDAT
  - # minimizes performance loss in high-interrupt-rate workload
- Extended DAT support to quad-core mobile processors
  - \* achieved in the same way as Deeper Sleep state
    - core idleness information is shared
    - \* each site locally resolves whether or not to allow the processor to run at EDAT frequencies

## EDAT PRINCIPLES

#### # EDAT Frequency is fixed

- \* typically 267 or 333 MHz over max core frequency
- Running half of available cores at EDAT frequencies while the remaining half remain idle will not exceed TDP limitations
- EDAT frequency is requested via the SpeedStep interface
- EDAT transition will only happen when the appropriate number of cores are idle and the operating system requests the highest performance (P) state
- If the operating system requests the P-state, the processor will run at guaranteed frequencies if enough cores are not idle

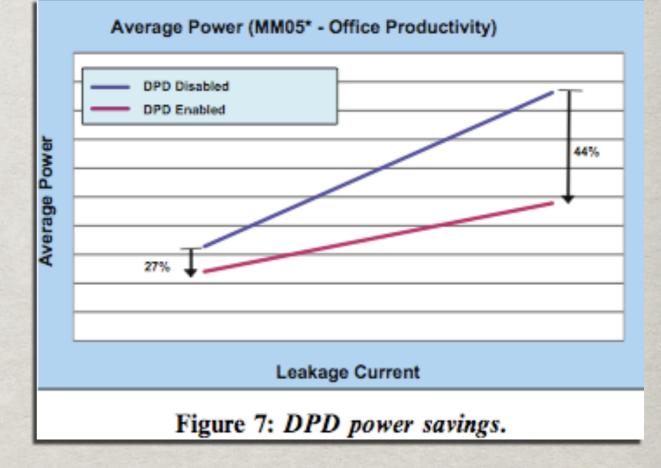




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  - Deep Power Down Results
  - CC3 Results
  - Deeper Sleep state and EDAT Results

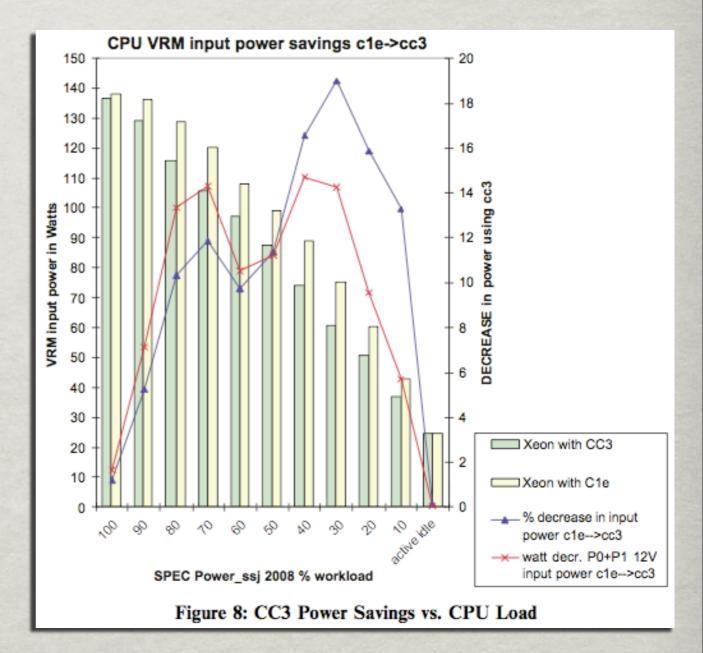
### DEEP POWER DOWN RESULTS

- Benchmarked using MobileMark 2005 (MM05)
  - \* average power consumption reduced by 27 to 44 percent
  - \* testing done on Intel Customer Reference Board platform
    - fresh build of Windows
      XP
  - power measured by sensing voltage and current during the MM05 run and averaging it



## CC3 RESULTS

- Intel Customer Reference Board platform with Seaburg chipset and ESB 2
- SPECpower\_ssj2008 benchmark
- # compared with C1E only enabled
- power consumption reduced by 0 percent at complete idle to 10-20 percent at medium loads
- power savings decreased at maximum loads due to time in C1E or CC3 decreasing



## DEEPER SLEEP STATE AND EDAT RESULTS

- Deeper Sleep state
  - Measurements done under operating system idle conditions
  - Idle power consumption decreased by 40-60 percent
- ✤ EDAT
  - SPECInt2000, SPECFP2000, and two-threaded counterparts used for benchmarks
  - \* performance increased by 5 to 8 percent
  - # 11 percent frequency boost over guaranteed frequency
  - # Hysteresis measured with SPEC2000 workload with 1,000 interrupts/sec timer
    - # used to tune hysteresis post-silicon
    - recovered over half of lost performance gains due to high interrupt rates



# QUESTIONS?